

REMARKS

Applicants respectfully request favorable reconsideration of this application, as amended.

The title of the invention has been amended in accordance with the Examiner's recommendation.

The specification (including the abstract) has been editorially revised to place this application in better form for issue. The informalities noted by the Examiner have been appropriately addressed. To facilitate entry of the changes, a substitute specification has been provided, together with a marked-up version showing the changes. No new matter has been added.

Without acceding to the outstanding claim rejections, the claims have been amended to avoid the alleged indefiniteness and otherwise to clarify the invention intended to be claimed. At least as presently amended, the claims clearly distinguish patentably from Figs. 19, 20 and 21 of the Applicants' disclosure.

Independent Claim 1 has been amended to clarify the arrangement of the bonding pads of the memory chip and the semiconductor chip and certain connections thereof to the bonding leads of the package substrate. As now set forth in Claim 1, the memory chip includes first bonding pads for address arranged along a first side of the memory chip, and second bonding pads for data arranged along a second side

which faces the first side in an opposed manner. The package substrate includes first bonding leads arranged along a first side of the package substrate corresponding to the first side of the memory chip, and second bonding leads arranged along a second side of the package substrate corresponding to the second side of the memory chip. The semiconductor chip includes, *inter alia*, third bonding pads arranged along a first side thereof and fourth bonding pads arranged along a second side thereof which faces the third side in an opposed manner. As now particularly set forth, the first and third bonding pads are connected in common to the first bonding leads of the package substrate, and the second and fourth bonding pads are connected in common to the second bonding leads of the package substrate.

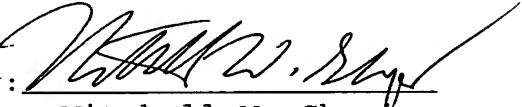
As will be evident, Figs. 19, 20 and 21 of Applicants' disclosure lack the common connection arrangements of the bonding pads with the bonding leads as set forth in amended Claim 1 described above.

Accordingly, the rejection under § 102(b) should be withdrawn, and Claim 1, as well as its dependents (including previously withdrawn Claims 11 and 12 subject to rejoinder), should now be allowed.

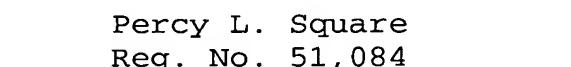
An early Notice of Allowance is respectfully solicited.

The Commissioner is hereby authorized to charge to Deposit Account No. 50-1165 any fees under 37 C.F.R. §§ 1.16 and 1.17 that may be required by this paper and to credit any overpayment to that Account. If any extension of time is required in connection with the filing of this paper and has not been requested separately, such extension is hereby requested.

Respectfully submitted,


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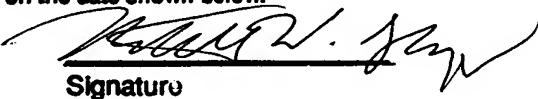
May 11, 2005

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date shown below.

5-11-05

Date



Signature

AMENDMENTS TO THE DRAWINGS:

Please substitute the attached replacement sheets for the sheets containing Figs. 19, 20 and 21 of the drawings as originally filed. These figures have been labeled as prior art.